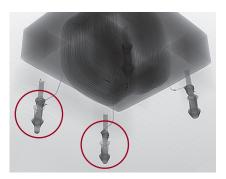




iX7059 Heavy Duty Inspection

High-precision X-ray system with fast inline handling of heavy objects

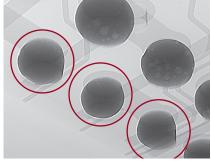
Fully Automatic Inspection for Solid Inspection Objects on Workpiece Carriers



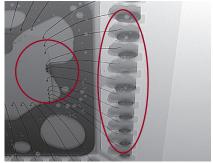
Transformer including THT terminals with varying fill levels



Poor THT solder joint, insufficient degree of filling



Head-in-pillow defect



Poor QFN, insufficient solder volume

Reliable inspection for heavy, solid and encased components thanks to powerful X-rays

Precise solder joint inspection of power electronics protects against overheating

Intelligent void check – identifying and measuring air inclusions for flawless heat dissipation

Maximum-speed 3D X-ray technology combined with special handling concept meets the highest throughput requirements

Inline system with minimal footprint

Intuitive operating software for fast programming and extremely simple verification

Service, hotline support and remote maintenance worldwide

Power electronics are a key component in the fields of electromobility, telecommunications and renewable energies. Fully automated 3D X-ray inspection is the first choice when it comes to ensuring that high-power electronics components function perfectly. Ultimately, targeted inspection is the only way to guarantee the flawless product quality needed to ensure the necessary high efficiency and functional reliability over the long term. iX7059 Heavy Duty Inspection is an advanced inline X-ray solution that uses innovative inspection technology and a special handling concept to inspect electronic assemblies and mechanical components on goods carriers.



Invest in cutting-edge 3D X-ray technology, customdesigned for the requirements of power electronics, e.g. especially for electric vehicles (EV)

The iX7059 Heavy Duty Inspection was designed especially for high-precision, rapid inspection of large assemblies including, for example, high-voltage/power electronics which are integrated in sensitive and safety-relevant end products. Essential criteria include here perfect safety, lasting functionality and high reliability. The machine is based on a compact system design, perfect-fit transport for large, heavy inspection objects on workpiece carriers and uniquely powerful 3D X-ray technology with high levels of radiation.



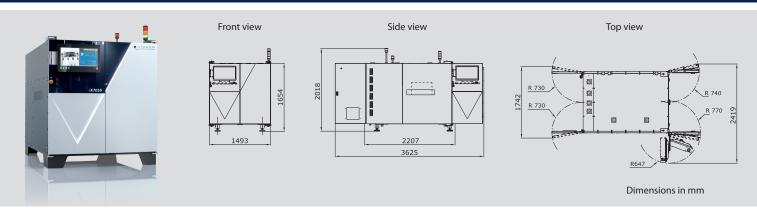
Special transport concept for handling assemblies on workpiece carriers or in solder frames

Depending on the application, the complex inspection objects can be irradiated with 130 kV or, as an option, up to 180 kV. As a result, the high-performance X-ray tube can be used to reliably inspect extremely solid electronics without damaging the components. The 3D technology produces the **best analysis results** based on the uniquely fast image acquisition approach **Evolution 5**.

In cases where high currents are flowing or are converted, defective solder joints can subsequently lead to overheating if they are too slender, for example. Hollow areas, known as voids, in surface solder joints, can lead to overheating if there is an excessive number of them or their diameter is too large. The **broad inspection scope** of the iX7059 Heavy Duty Inspection system extends to damage, twisted, missing or incorrect components, concealed blow holes/voids as well as the degree of filling and pin heights of THT solder jonts.

The high-precision system stands out thanks to a resolution of 8 μ m to 30 μ m, depending on the configuration. The **integrated computer tomography** (optional) delivers excellent images of layers in premium quality, making verification very easy. Inspection objects and workpiece carriers with dimensions of up to 500 mm x 500 mm and a **weight of up to 40 kg** can be inspected for all defects, completely automatically and at high throughput rates. The system can be seamlessly integrated into the production line or final assembly line, and networking to **implement smart factory concepts** is also an option.

Technical Specifications



X-ray technology X-ray tube High voltage Sealed microfocus X-ray tube 130 kV (up to 180 kV optional)	
High voltage 130 kV (up to 180 kV optional)	
Tube current 300 μA (500 μA)	
Detector Flat panel detector type FPD T2 (FPD T3	and T4 optional), 14-bit grayscale depth
Resolution 8 - 30 µm/pixel*	
3D image capture mode Evolution 4 as standard, Evolution 5 and image recordings	l Evolution 6 optional for unique dynamic
X-ray cabinet Designed to meet requirements for fully German Radiation Protection Act (StrlSc Ordinance (StrlSchV). Radiation leakage	:hG) and German Radiation Protection
Detector configuration 1 FPD on xy-table	
Software User interface Viscom vVision/EasyPro	
Statistical process control Viscom vSPC/SPC, open interface (option	nal)
Verification station Viscom vVerify/HARAN	
Remote diagnosis Viscom SRC (optional)	
Programming station Viscom PST34 (optional)	
Operating system Windows®	
Processor Intel® Core™ i7	
Inspection object/ Inspection object size Up to 500 mm x 500 mm (19.6" x 19.6") ((L×W)*
workpiece carrier Inspection object weight Up to 40 kg (88.2 lbs)	
Transfer height $860 - 980 \text{ mm} \pm 20 \text{ mm} (33.8" - 38.5" \pm 0)$	0.7")
Width adjustment Via manual adjustment	
Support area 50 mm (1.9")	
Transport clearance 150 mm (5.9") as standard, more on requ	uest
Other system data Positioning unit Synchronous linear motor	
Interfaces SECS/GEM, SMEMA, IPC Hermes (optional	al)
Power requirements 400 V (other voltages on request), 3P/N/	PE, 8 A, 4 – 6 bar working pressure
System dimensions 1493 mm x 1654 mm x 2207 mm (58.7")	x 65.1" x 86.8") (W x H x D)
Line integration dimension +30 mm (1.1") on both sides	
Weight 2500 – 3000 kg (5511.5 – 6613.8 lbs)*	

Specifications and other system information are subject to change without notice and may differ from the information displayed at the time of ordering.

*Depending on the configuration